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PRIMA-SOLDER
EG8050

Stress-Free
One or Two Component
Reworkable
Epoxy Paste Adhesive

IDEAL FOR:

Large Area Die
Substrate/Component
Reworkability
Mismatched CTE's
Solder Replacement

DESCRIPTION:

EG8050 is an electrically conductive, silver filled epoxy which exhibits outstanding flexibility for bonding materials with highly mismatched CTE's (i.e., alumina to aluminum, silicon to copper).

It can be readily reworked at 80-100°C and is ideal for applications such as large area die attach and substrate attach because of its ability to bond materials with highly mismatched CTE.

AVAILABILITY:

EG8050 is available in syringes for automatic needle dispense applications or in jars. Both viscosity and thixotropic index can be modified to your specific needs. EG8050 can be premixed and frozen.

APPLICATION PROCEDURES:

- (1) Mix adhesive in 1:1 ratio. (Note: In kit form, Viscosity of Part A > Viscosity of Part B)
- (2) Dispense adhesive onto clean substrate.
- (3) Cure according to one of the recommended schedules.

**If material is premixed and frozen, thaw for 30 minutes and cure according to one of the recommended schedules.

TYPICAL PROPERTIES*

Electrical Resistivity (150 °C/ 60 min)	<4x10 ⁻⁴ ohm-cm
Dielectric Strength (Volts/mil)	N/A
Glass Transition Temp.(°C)	-20
Current Carrying Capabilities	35 Amp/mm ²
Lap-Shear Strength	1000 psi 6.9 N/mm ²
Device Push-off Strength	1800 psi 12.4 N/mm ²
Cured Density (gm/cc)	4.0
Thermal Conductivity	55 Btu-in/hr-ft ² -°F 7.9 W/m-°C
Linear Thermal Expansion Coeff. (ppm/°C)	120
Maximum Continuous Operation Temp. (°C)	130
Avg. Viscosity(0.5 rpm, 24°C) (Brookfield DV-1, spindle CP51)	190,000 cp

* Properties given are typical values and not intended for use in preparing specifications. The user is advised to evaluate the product in the manner the product is intended to be used in manufacturing and in the final product.

****CURE SCHEDULES:**

<u>Temperature</u>	<u>Time</u>
25°C	120 hr
80°C	8 hr
125°C	2 hr
150°C	1 hr

SHELF LIFE:

<u>Storage temperature</u>	<u>Shelf Life</u>
**25°C	1 yr in original sealed package

**Shelf life is for unmixed components. If premixed: -40°C for 6 months in original sealed package. After mixing, pot life is 4 hours at 25°C.

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